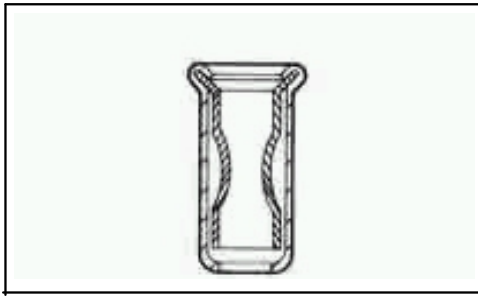


**Product Details for 3 -331272 -9**



**3 -331272 -9**

[Pending  
Obsolescence  
Contact Product  
Information Center](#)

**Discrete Sockets**

[Not ELV or RoHS Compliant](#) [\(Find RoHS Compliant Alternates\)](#)

**Product Highlights:**

- ? Socket
- ? Mating Pin Dia. Range = .46 - .51 mm
- ? Socket Length = 3.51 mm
- ? Sleeve Style = Open Bottom
- ? Tin Sleeve Plating

[View all Features](#)

**Quick Links**

- [Check Pricing & Availability](#)
- [Search for Tooling](#)
- [Product Feature Selector](#)
- [Contact Us About This Product](#)

**Documentation & Additional Information**

**Product Drawings:**

- ? [MINIATURE SPRING SOCKET ASSEMBLY, SERIES 2](#) (PDF, English)

**Catalog Pages/Data Sheets:**

- ? None Available

**Product Specifications:**

- ? None Available

**Application Specifications:**

- ? None Available

**Instruction Sheets:**

- ? None Available

**CAD Files:**

- ? None Available

**Additional Information:**

- ? [Product Line Information](#)

**Related Products:**

- ? [Tooling](#)

[List all Documents](#)

**Product Features** (Please use the Product Drawing for all design activity)

**Product Type Features:**

- ? Product Type = Socket
- ? [Socket Length \(mm \[in\]\)](#) = 3.51 [0.138]
- ? [Sleeve Style](#) = Open Bottom
- ? [Sealant](#) = Without
- ? Sleeve Material = Copper
- ? Recommended Hole Size (mm [in]) = 1.32 [0.052]

**Body Related Features:**

- ? [Mating Pin Dia. Range \(mm \[in\]\)](#) = 0.46 - 0.51 [0.018 - 0.020]
- ? Spring Material = Beryllium Copper

**Contact Related Features:**

- ? [Sleeve Plating](#) = Tin
- ? [Contact Spring Plating](#) = Gold (30)
- ? [Contact Material](#) = Beryllium Copper

**Configuration Related Features:**

- ? [Insertion Method](#) = Hand/Semi -Automatic

**Industry Standards:**

- ? Government/Industry Qualification = No
- ? [RoHS/ELV Compliance](#) = Not ELV/RoHS compliant
- ? [Lead Free Solder Processes](#) = Wave solder capable to 240°C, Wave solder capable to 260°C, Wave solder capable to 265°C, Reflow solder capable to 245°C, Reflow solder capable to 260°C, Pin -in -Paste capable to 245°C, Pin in -Paste capable to 260°C

**Operation/Application:**

- ? Application = Production

**Packaging Related Features:**

- ? [Packaging Method](#) = Loose Piece

**Other:**

- ? Brand = AMP